

Features

- Frequency range : 8MHz to 54MHz
- Ceramic SMD package
- Seam sealing
- External dimensions (mm)
L : 5.0 x W : 3.2 x H : 0.9
- RoHS compliant & Pb free

Applications

- Bluetooth, Wireless LAN
- Cellular phone, Pager, DSC
- Display, TV
- Computer peripherals
- Consumer products

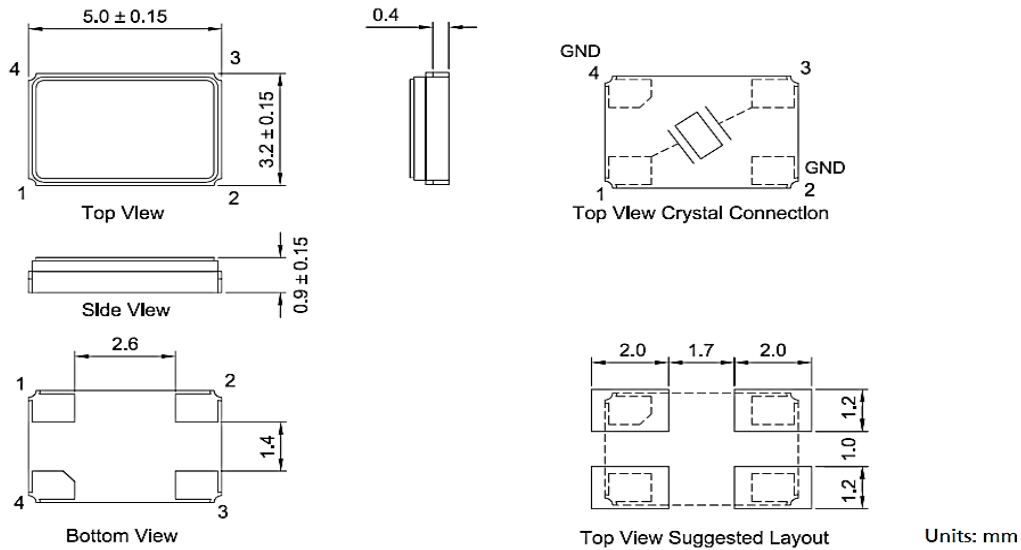
Electrical Characteristics

Item		7B	Conditions
Frequency Range	F_0	8MHz ~ 54MHz	
Frequency Tolerance	F_{tol}	$\pm 50\text{ppm}$, $\pm 30\text{ppm}$, $\pm 10\text{ppm}$	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	$\pm 50\text{ ppm}$	-20°C ~ +70°C
		$\pm 30\text{ ppm}$	
		$\pm 10\text{ ppm}$	
		$\pm 30\text{ ppm}$	-40°C ~ +85°C
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-40°C ~ +85°C	
Shunt Capacitance	C_0	5pF Max. (2pF Typ.)	
Drive Level	D_L	1 ~ 200μW (100μW Typ.)	
Load Capacitance	C_L	10pF, 12pF, 16pF, 18pF, 20pF	
Aging	F_{aging}	$\pm 3\text{ ppm Max.}$	at 25°C $\pm 3^\circ\text{C}$, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

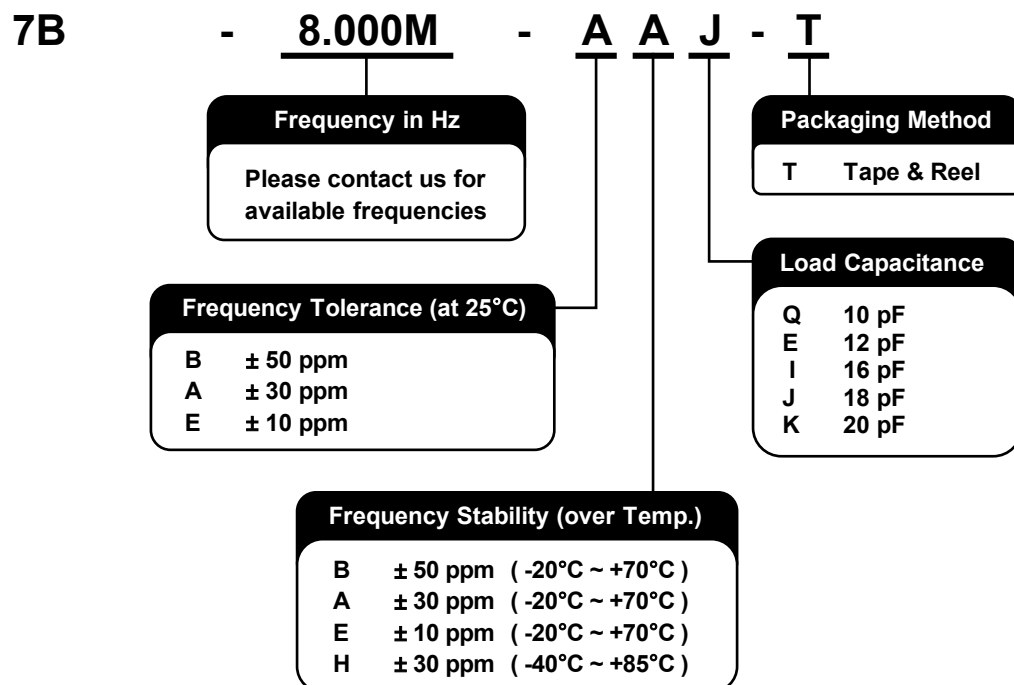
Motional Resistance (ESR)

Fundamental	
8 ~ 11 MHz	80Ω Max.
12 ~ 54 MHz	40Ω Max.

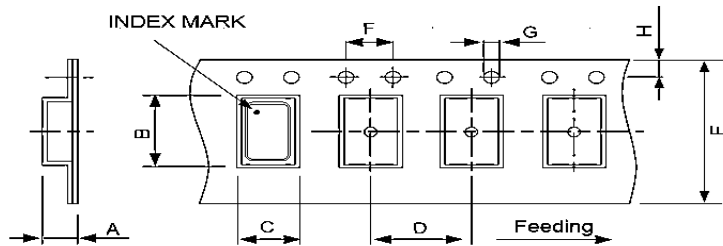
Dimensions



Ordering Information

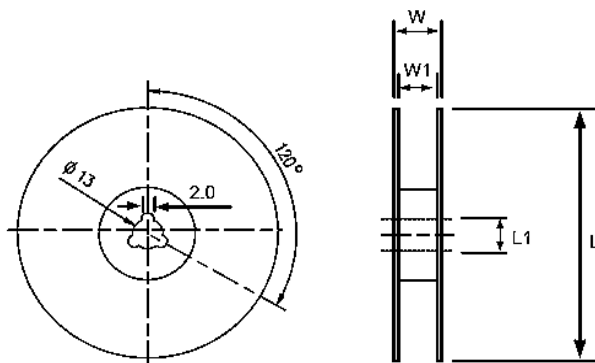


Packing



DIMENSIONS	A	B	C	D	E	F	G	H
	1.65±0.10	5.40±0.10	3.50±0.10	8.00±0.10	12.00±0.30	4.00±0.10	1.55±0.10	1.75±0.10

(Unit: mm)



DIMENSIONS	L	L1	W	W1
	180±1.00	13±0.50	16.5±0.20	12±0.10

(Unit: mm)

Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

